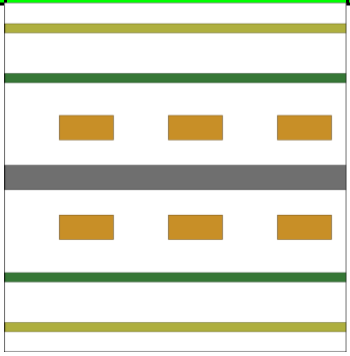
Board Stack Report

Stack Up		Layer Stack			
Layer	**Board Layer Stack**	**Name**	**Material**	**Thickness**	**Constant**
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.40mil	
5		Dielectric1	FR-4 High Tg	59.20mil	4.8
6		Bottom Layer	Copper	1.40mil	
7		Bottom Solder	Solder Resist	0.40mil	3.5
8		Bottom Overlay			
9		Bottom Paste			
	Height : 62.80mil				

Orderable: N/A		Designed for: Piblic Released
TID #: TIDA-060042		Project Title: Series RTD Sensing
Number: TIDA-060042	Rev: E1	Sheet Title: =title
SVN Rev: Not in version control		Assembly Variant: 001
Drawn By:=DrawnBy		File: Current_Biasing.SchDoc
Engineer: Jiajun Guan		Contact: http://www.ti.com/support

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